



Express Mail No. EV758927720US

Attorney Docket No. 108298746US
Disclosure No. 03-1029.00/US

PTO/SB/08a/b (07-05)

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Substitute for form 1449A/B/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)		Complete If Known			
		Application Number	10/723,363-Conf. #9952		
		Filing Date	November 26, 2003		
		First Named Inventor	Mark E. Tuttle		
		Art Unit	2621- 2624		
		Examiner Name	Not Yet Assigned Amara Abdi		
Sheet	1	of	6	Attorney Docket Number	108298746US

U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)				
/A.A./ ↓						

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